Application Number 10/639,055 Amendment dated September 23, 2005 Response to Office action of July 25, 2005

Amendments to the Specification:

Please replace paragraph [0027] with the following amended paragraph:

[0027] Electrodes 1 and 5 have nanoscale roughness that prevents them from being brought into sufficiently close contact to allow tunnelling. In one embodiment heat, the electrodes are moved apart, the housing is evacuated, and heat is applied to the assembly shown in Figure 5 via thermal interfaces 30 and 35.

Please replace paragraph [0031] with the following amended paragraph:

[0031] In another further embodiment, the environment comprises the operating conditions for the device, whereby a voltage bias is applied between the electrodes and/or a temperature differential is applied between them, thus operating the device as a gap diode. The gap diode may be, for example, a thermo-tunneling gap diode, a thermionic gap diode or a gap diode heat pump. This 'burn-in' process involves operating the device, either with a fixed diode spacing, or with a variable one (whilst the latter is preferable-would be better, the former is cheaper).